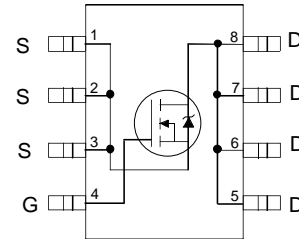


Features

- $V_{DS} (V) = 40V$
- $R_{DS(ON)} < 7.5m\Omega$ ($V_{GS} = 10V$)
- $R_{DS(ON)} < 9 m\Omega$ ($V_{GS} = 4.5V$)

Applications

- High Frequency DC-DC Converters with Synchronous Rectification
- Lead-Free



Benefits

- Ultra-Low Gate Impedance
- Very Low $R_{DS(on)}$ at 4.5V V_{GS}
- Fully Characterized Avalanche Voltage and Current

Absolute Maximum Ratings

Symbol	Parameter	Max.	Units
V_{DS}	Drain-Source Voltage	30	V
V_{GS}	Gate-to-Source Voltage	± 12	V
$I_D @ T_A = 25^\circ C$	Continuous Drain Current, $V_{GS} @ 10V$	15	A
$I_D @ T_A = 70^\circ C$	Continuous Drain Current, $V_{GS} @ 10V$	12	
I_{DM}	Pulsed Drain Current ^①	120	
$P_D @ T_A = 25^\circ C$	Maximum Power Dissipation ^③	2.5	W
$P_D @ T_A = 70^\circ C$	Maximum Power Dissipation ^③	1.6	W
	Linear Derating Factor	0.02	W/ $^\circ C$
T_J, T_{STG}	Junction and Storage Temperature Range	-55 to + 150	$^\circ C$

Thermal Resistance

Symbol	Parameter	Typ.	Max.	Units
$R_{\theta JA}$	Junction-to-Ambient ^④		50	$^\circ C/W$

Notes:

- ① Repetitive rating; pulse width limited by max. junction temperature.
- ② Starting $T_J = 25^\circ C$, $L = 9.4mH$
 $R_G = 25\Omega$, $I_{AS} = 8.0A$.
- ③ Pulse width $\leq 400\mu s$; duty cycle $\leq 2\%$.
- ④ When mounted on 1 inch square copper board, $t < 10$ sec

Static @ T_J = 25°C (unless otherwise specified)

	Parameter	Min.	Typ.	Max.	Units	Conditions
V _{(BR)DSS}	Drain-to-Source Breakdown Voltage	30			V	V _{GS} = 0V, I _D = 250μA
ΔV _{(BR)DSS/ΔT_J}	Breakdown Voltage Temp. Coefficient		0.029		V/°C	Reference to 25°C, I _D = 1mA
R _{DS(on)}	Static Drain-to-Source On-Resistance		6.0	7.5	mΩ	V _{GS} = 10V, I _D = 15A ④
			6.9	9		V _{GS} = 4.5V, I _D = 12A ④
			10	2		V _{GS} = 2.8V, I _D = 3.5A ④
V _{GS(th)}	Gate Threshold Voltage	0.6		2.0	V	V _{DS} = V _{GS} , I _D = 250μA
I _{DSS}	Drain-to-Source Leakage Current			20	μA	V _{DS} = 24V, V _{GS} = 0V
				100		V _{DS} = 24V, V _{GS} = 0V, T _J = 125C
I _{GSS}	Gate-to-Source Forward Leakage			200	nA	V _{GS} = 12V
	Gate-to-Source Reverse Leakage			-200		V _{GS} = -12V

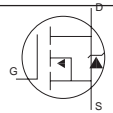
Dynamic @ T_J = 25°C (unless otherwise specified)

Symbol	Parameter	Min.	Typ.	Max.	Units	Conditions
g _{fs}	Forward Transconductance	44			S	V _{DS} = 10V, I _D = 15A
Q _g	Total Gate Charge		37	56	nC	I _D = 15A
Q _{gs}	Gate-to-Source Charge		8.9	13		V _{DS} = 24V
Q _{gd}	Gate-to-Drain ("Miller") Charge		13	20		V _{GS} = 5.0V ③
Q _{oss}	Output Gate Charge		23	35		V _{GS} = 0V, V _{DS} = 16V
t _{d(on)}	Turn-On Delay Time		17		ns	V _{DD} = 15V
t _r	Rise Time		18			I _D = 1.0A
t _{d(off)}	Turn-Off Delay Time		51			R _G = 6Ω
t _f	Fall Time		44			V _{GS} = 4.5V ③
C _{iss}	Input Capacitance		3480		pF	V _{GS} = 0V
C _{oss}	Output Capacitance		870			V _{DS} = 25V
C _{rss}	Reverse Transfer Capacitance		100			f = 1.0MHz

Avalanche Characteristics

Symbol	Parameter	Typ.	Max.	Units
E _{AS}	Single Pulse Avalanche Energy②		300	mJ
I _{AR}	Avalanche Current②		15	A

Diode Characteristics

Symbol	Parameter	Min.	Typ.	Max.	Units	Conditions
I _S	Continuous Source Current (Body Diode)			2.5	A	MOSFET symbol showing the integral reverse p-n junction diode. 
I _{SM}	Pulsed Source Current (Body Diode) ①			120		
V _{SD}	Diode Forward Voltage			1.2	V	T _J = 25°C, I _S = 2.5A, V _{GS} = 0V ③
t _{rr}	Reverse Recovery Time		64	96	ns	T _J = 25°C, I _F = 2.5A, V _R = 20V
Q _{rr}	Reverse Recovery Charge		99	150	nC	di/dt = 100A/μs ③

TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

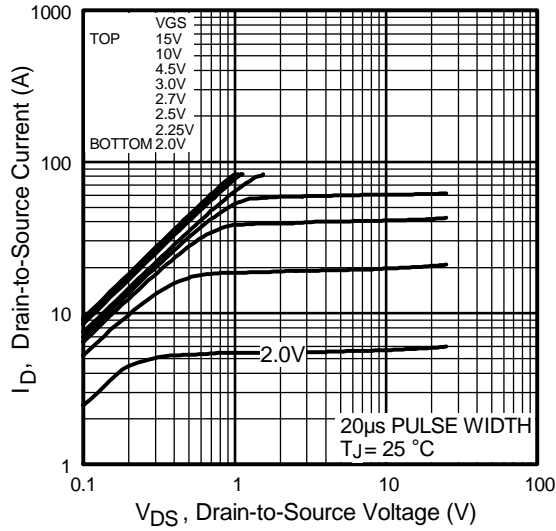


Fig 1. Typical Output Characteristics

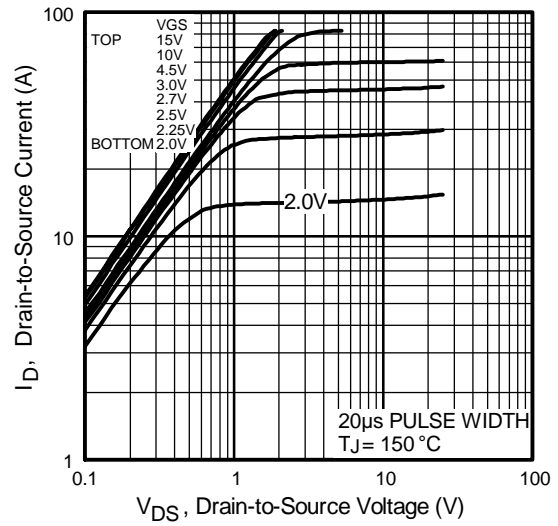


Fig 2. Typical Output Characteristics

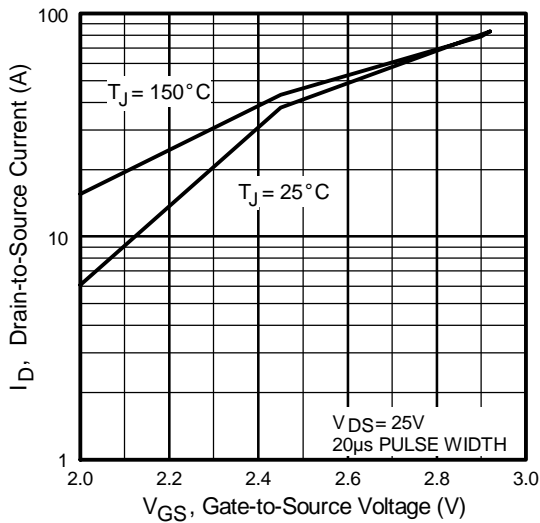


Fig 3. Typical Transfer Characteristics

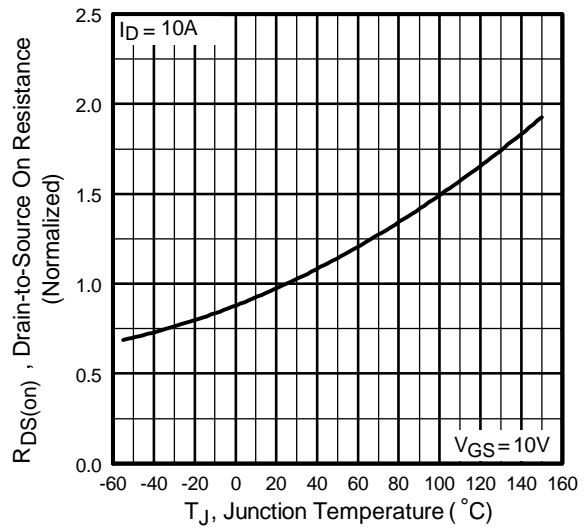


Fig 4. Normalized On-Resistance Vs. Temperature

TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

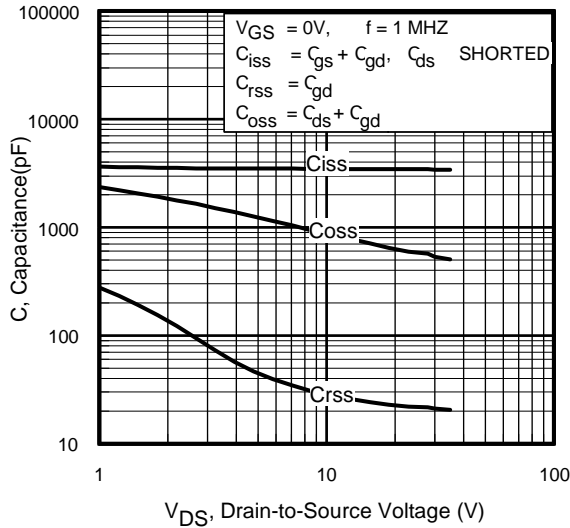


Fig 5. Typical Capacitance Vs. Drain-to-Source Voltage

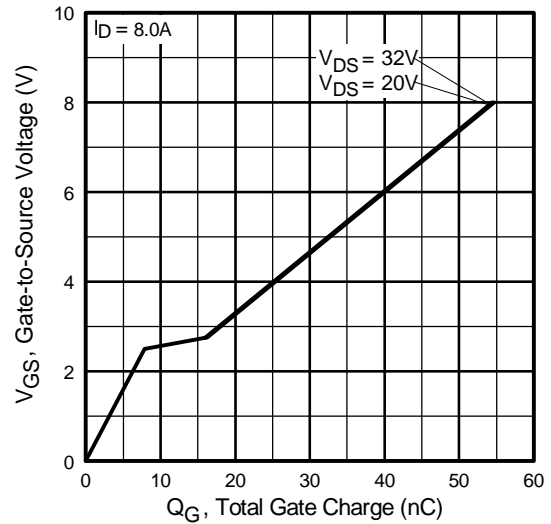


Fig 6. Typical Gate Charge Vs. Gate-to-Source Voltage

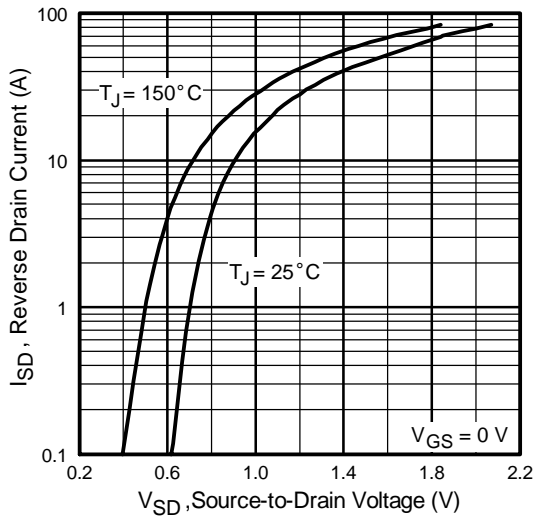


Fig 7. Typical Source-Drain Diode Forward Voltage

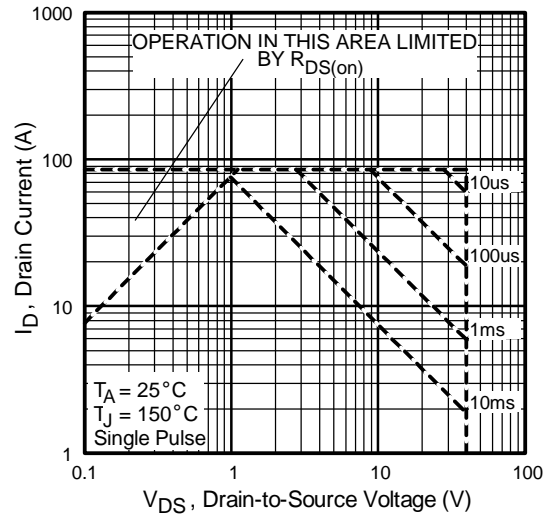


Fig 8. Maximum Safe Operating Area

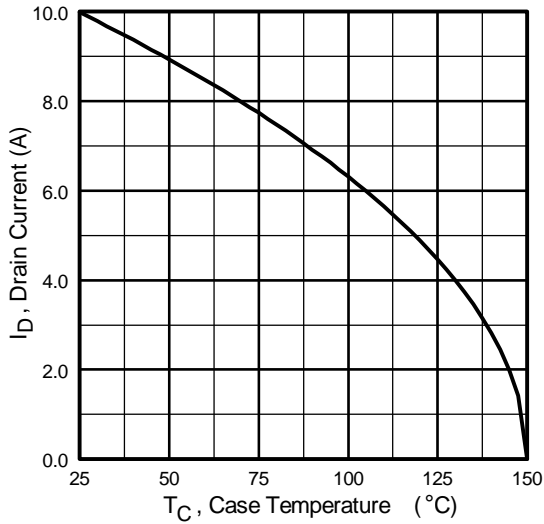


Fig 6. On-Resistance Vs. Drain Current

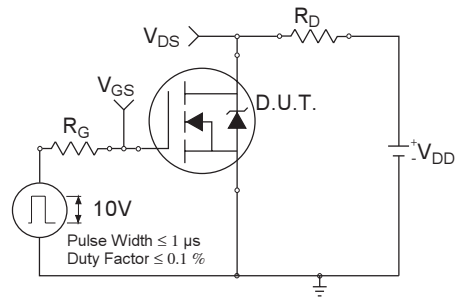


Fig 10a. Switching Time Test Circuit

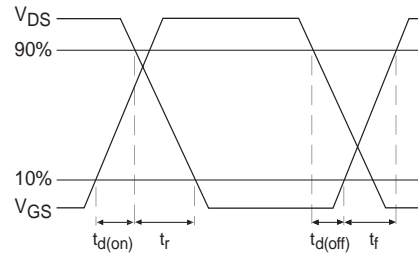


Fig 10b. Switching Time Waveforms

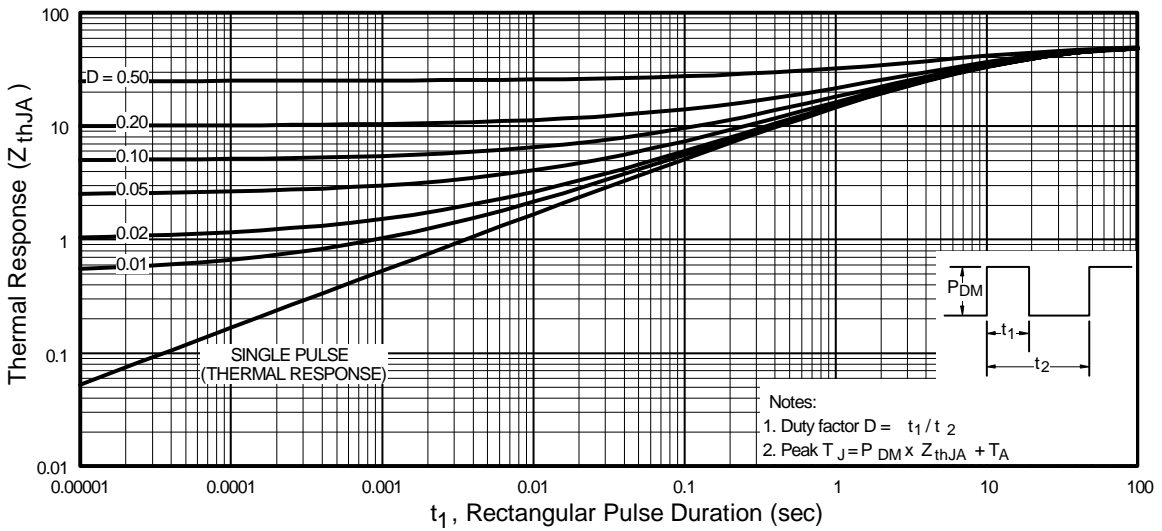


Fig 10. Maximum Effective Transient Thermal Impedance, Junction-to-Ambient

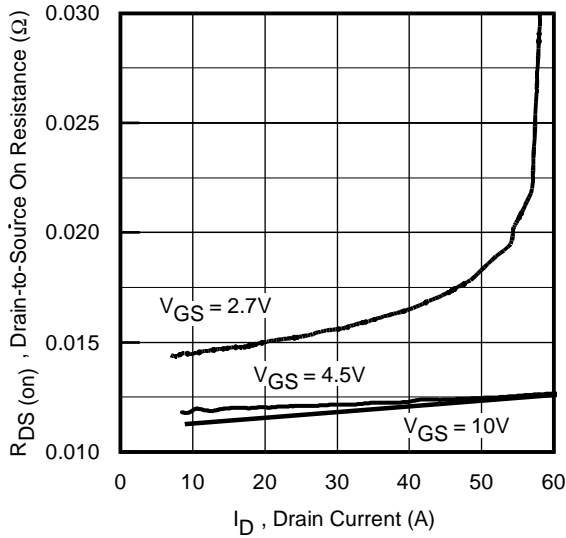


Fig 12. On-Resistance Vs. Drain Current

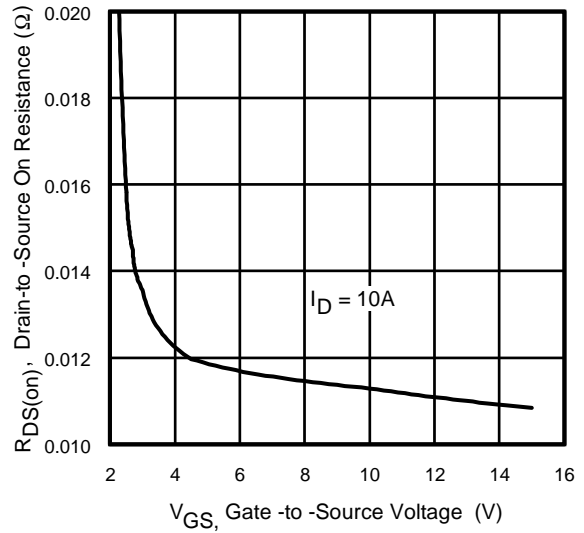


Fig 13. On-Resistance Vs. Gate Voltage

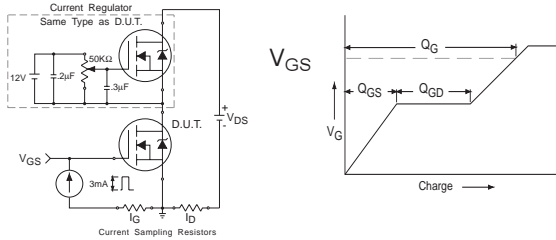


Fig 13a&b. Basic Gate Charge Test Circuit and Waveform

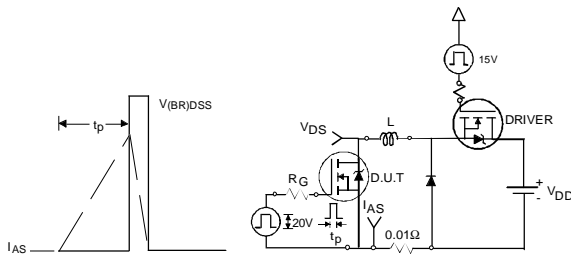


Fig 14a&b. Unclamped Inductive Test circuit and Waveforms

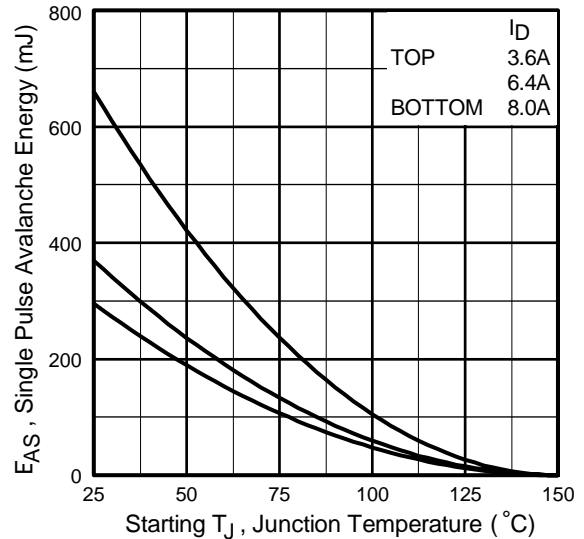
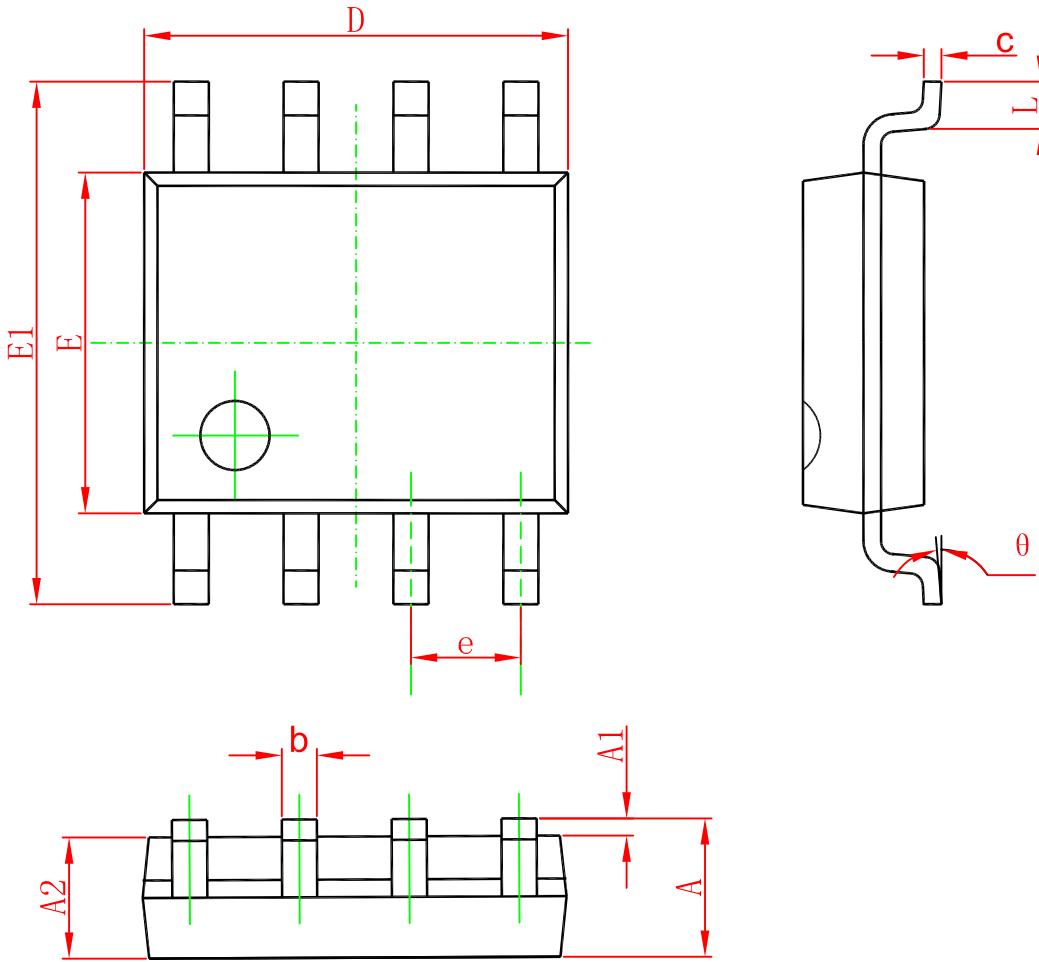


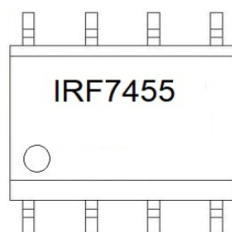
Fig 14c. Maximum Avalanche Energy Vs. Drain Current

SOP-8



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	1.350	1.750	0.053	0.069
A1	0.100	0.250	0.004	0.010
A2	1.350	1.550	0.053	0.061
b	0.330	0.510	0.013	0.020
c	0.170	0.250	0.006	0.010
D	4.700	5.100	0.185	0.200
E	3.800	4.000	0.150	0.157
E1	5.800	6.200	0.228	0.244
e	1.270(BSC)		0.050(BSC)	
L	0.400	1.270	0.016	0.050
θ	0°	8°	0°	8°

Marking



Ordering information

Order code	Package	Baseqty	Deliverymode
IRF7455TR	SOP-8	3000	Tape and reel